

----- ABSTRACTS NOW DUE FEBRUARY 28, 2019 -----



IMAPS 2019 Technical Track on:

Advanced Process & Materials (Enabling Technologies)

Track Co-Chair:	Track Co-Chair:
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The objective of this track is to have a unique forum that brings together scientists, engineers, manufacturers, academia, and business people from around the world who have been working in the area of advanced materials development, fabrication, and assembly processes, including specific track emphases on additive manufacturing, flexible hybrid electronic packaging applications, advanced substrate technology and state of the art use of wirebond technology.

Abstracts are being requested on the following topics:

Substrate Technology	Novel Materials Polymers & Processes	Additive Manufacturing	Advanced Wirebond
Glass	Printed & Flexible Electronics	Assembly & Integration	Stacked & Tiered Die Packaging
Silicon	Biodegradable Electronics	Compliant Inks	Interposer Applications
Organic	New Thermal & Interconnect Materials	High Temperature Applications	Process Enhancements
Stretchable / flexible	High Temperature Materials	Scaling Technology for Fine Pitch	Reliability
Dielectrics	Low Temperature Solders & Soldering	Advanced Processing Equipment	New Interconnect Materials
Via Processes	Diffusion Bonding		Power Applications

Those wishing to present at IMAPS 2019 Boston must submit a 500+ word abstract electronically **no later than FEBRUARY 28, 2019**, using the on-line submittal form at www.imaps2019.org or www.imaps.org/abstracts.htm. Please contact Brian Schieman by email at bschieman@imaps.org if you have questions. **STUDENT AUTHORS:** upon abstract submission, please select "yes, I'm a full-time student" on the form and you will automatically be entered in the student competition.

If your abstract is selected, you will be asked to follow the speaker timeline: - Speaker Acceptance/Rejection (April 1); - First Paper to Peer Review (May 15); - Peer Review feedback to authors (July 1); - Final/corrected Papers (August 1); - Speaker must register before (August 15); - BIO due (September 15); Speaker Breakfast (morning of your session); and - Slides/Presentation ready (on/before September 30).

1 "Best of Track" Outstanding Paper with Cash Award
1 Best Paper of the Symposium – Chosen from "Best of 5 Tracks"
IMAPS Microelectronics Educational Foundation Student Paper Awards
The Foundation is offering CASH AWARDS to the best papers submitted and presented by students at IMAPS Symposium.